L Number	Hits	Search Text	DB	Time stamp
Livuilibei	0	156/\$.ccls. and (anisotropical near1 tape) and (cut or	USPAT;	2004/05/01 14:19
	•	"cut-off") and conductive	US-PGPUB;	,
1			EPO; JPO;	
'			DERWENT;	
i .			IBM TDB	
	o	156/\$.ccls. and (anisotropical near1 tape) and conductive	USPAT;	2004/04/30 14:00
-	· ·	100/0.0010. and (amboutopious trous time)	US-PGPUB;	'
	ì	•	EPO; JPO;	
· .			DERWENT;	
			IBM_TDB	
	0	156/\$.ccls. and (anisotropical near2 tape) and conductive	USPAT;	2004/04/30 14:00
-	٦	100/4.000. and (amount please the stage of and seems	US-PGPUB;	
			EPO; JPO;	
	•		DERWENT;	
			IBM_TDB	
	0	156/\$.ccls. and (anisotropical near3 tape) and conductive	USPAT;	2004/04/30 20:19
-	U	150/\$.ccis. and (amsomopical hears tape) and conductive	US-PGPUB;	
			EPO; JPO;	
:	:	,	DERWENT;	
			IBM_TDB	-
	_ [156/\$ cole, and (anisotronical near3 tane)	USPAT;	2004/05/02 11:48
-	0	156/\$.ccls. and (anisotropical near3 tape)	US-PGPUB;	
			EPO; JPO;	
	٠.		DERWENT;	
. 1			IBM_TDB	
	47	450(0 sele and (enjectronic near)	USPAT;	2004/04/30 14:12
-	17	156/\$.ccls. and (anisotropic near3 tape)	US-PGPUB;	200 1/0 1/00 1 1:12
1			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	1
			USPAT;	2004/04/30 19:30
-	0	83/\$ ccls. and (anisotropic near3 tape)	US-PGPUB;	2004/04/00 10:00
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
		20/0 to and (anicotronic maps? topo)	USPAT;	2004/04/30 14:24
-	22	29/\$.ccls. and (anisotropic near3 tape)	US-PGPUB;	2004/04/50 14.24
			EPO; JPO;	
		,	DERWENT;	•
			IBM_TDB	
1		450,050,0010		2004/05/02 11:24
-	375	(156/353).CCLS.	USPAT; US-PGPUB;	2007/00/02 11.24
1			EPO; JPO;	
			DERWENT;	
			IBM TDB	
1		(450/050) 001.0	USPAT;	2004/05/01 14:11
	418	(156/359) CCLS.	US-PGPUB;	2007/00/01 17:11
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
		(450,000) 001.0	USPAT;	2004/04/30 17:42
-	210	(156/360).CCLS.	US-PGPUB;	2007/07/00 17.72
			EPO; JPO;	
			DERWENT;	ľ
	1		IBM_TDB	2004/04/20 16:55
-	1	matsushita.asn. and (anisotropical near3 tape) and	USPAT;	2004/04/30 16:55
		conductive	US-PGPUB;	
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	

-	51	matsushita.asn. and (anisotropic near3 tape) and conductive	USPAT;	2004/05/02 10:58
	[US-PGPUB;	
	l i		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	617	(156/378).CCLS.	USPAT;	2004/05/01 14:06
			US-PGPUB;	
			EPO; JPO;	,
			DERWENT;	,
		•	IBM_TDB	
-	169	(156/379).CCLS.	USPAT;	2004/04/30 19:01
			US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
l -	o	83/\$.ccls. and (TCP) and (cut or "cut-off") and (measure or	USPAT;	2004/04/30 19:31
		measurement)	US-PGPUB;	
1	·	,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
l _	2401	83/\$.ccls. and (cut or "cut-off") and (measure or	USPAT;	2004/04/30 19:31
		measurement)	US-PGPUB;	
	.	, I	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	157	83/\$.ccls. and (cut or "cut-off") and (measure or	USPAT;	2004/04/30 20:16
		measurement) and (tape or film) and (circuit or electrode)	US-PGPUB;	
		, , , , , , , , , , , , , , , , , , , ,	EPO; JPO;	
1			DERWENT;	
			IBM_TDB	
1 _	0	(anisotropical near3 tape) and conductive and (cut or	USPAT;	2004/04/30 20:19
-		"cut-off") and (measure or measurement)	US-PGPUB;	
		,	EPO; JPO;	
			DERWENT,	
			IBM_TDB	
	26	(anisotropic near3 tape) and conductive and (cut or "cut-off")	USPAT;	2004/04/30 20:31
-	20	and (measure or measurement)	US-PGPUB;	
		una (modelaro el modelaron)	EPO; JPO;	
1			DERWENT;	, ·
			IBM_TDB	
.	301	(TCP) and conductive and (cut or "cut-off") and (measure or	USPAT;	2004/04/30 20:32
		measurement)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	1
1_	153	(TCP) and conductive and (cut or "cut-off") and (measure or	USPAT;	2004/04/30 20:32
		measurement) and (adhesive)	US-PGPUB;	
		,	EPO; JPO;	
1			DERWENT;	
1	-		IBM_TDB	
1_	0	83/\$.ccls. and (TCP or "tape carrier package") and	USPAT;	2004/04/30 20:54
		((temperature or thermal) near2 (compensation or	US-PGPUB;	
		comparation or measurement))	EPO; JPO;	
			DERWENT;	
	-		IBM_TDB	
_	6	156/\$.ccls. and (TCP or "tape carrier package") and	USPAT;	2004/04/30 21:01
-		((temperature or thermal) near2 (compensation or	US-PGPUB;	
		comparation or measurement))	EPO; JPO;	
	ŀ	bomparation of moadaromonty)	DERWENT,	
			IBM_TDB	
	1	29/\$.ccls. and (TCP or "tape carrier package") and	USPAT;	2004/04/30 20:54
-	'	((temperature or thermal) near2 (compensation or	US-PGPUB;	
1	1	comparation or measurement))	EPO; JPO;	
	1		, _, _,	
	İ	Comparation of measurement)	DERWENT;	

-	79	(118/677).CCLS.	USPAT;	2004/05/01 14:47
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	634	(156/521).CCLS.	USPAT;	2004/05/01 15:52
			US-PGPUB;	
			EPO; JPO;	
	ĺ		DERWENT:	
			IBM TDB	
	0	156/\$.ccls. and (semiconductor same tape) and (temperature	USPAT;	2004/05/01 14:56
-	١	near4 compensation)	US-PGPUB;	2004/03/01 14.30
	,	l near4 compensation)	EPO; JPO;	
	1		DERWENT:	
	400	(450/007) 001 0	IBM_TDB	0004/05/04 44:40
-	183	(156/367).CCLS.	USPAT;	2004/05/01 14:48
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
-	0	156/\$.ccls. and (semiconductor same tape) and (size near4	USPAT;	2004/05/01 14:55
		compensation)	US-PGPUB;	
		, ,	EPO; JPO;	
]			DERWENT;	
		•	IBM_TDB	
1_	0	156/\$.ccls. and (semiconductor same tape) and (size near4	USPAT;	2004/05/01 14:55
1 -	١	correction)	US-PGPUB;	2004/00/01 14:00
		Correction)		
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/04 44 50
-	0	156/\$.ccls. and (semiconductor same tape) and (temperature	USPAT;	2004/05/01 14:56
		same compensation)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	0	156/\$.ccls. and (semiconductor near20 tape) and	USPAT;	2004/05/01 14:56
		(temperature near20 compensation)	US-PGPUB;	
		, ,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	o	83/\$.ccls. and (semiconductor near20 tape) and (temperature	USPAT;	2004/05/01 14:56
	Ĭ	near20 compensation)	US-PGPUB;	
		nearzo compensation)	EPO; JPO;	
			DERWENT;	
	, 1		IBM_TDB	
		20/6 cole and (comican distant mass 20 to) and (to		2004/05/04 45:00
-	1	29/\$.ccls. and (semiconductor near20 tape) and (temperature	USPAT;	2004/05/01 15:08
'	ļ	near20 compensation)	US-PGPUB;	
[EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	29/\$.ccls. and (TCP or "tape carrier package") and	USPAT;	2004/05/01 16:04
		(temperature near20 compensation)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	44	29/\$.ccls. and (adhesive) and (temperature near20	USPAT;	2004/05/01 15:29
.		compensation)	US-PGPUB;	
		, ,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	22	156/\$.ccls. and (adhesive) and (temperature near20	USPAT;	2004/05/01 15:30
-	~~	compensation) and (tape or film)	US-PGPUB;	±00-700/01 10.00
		componsation) and tape or min)	EPO; JPO;	
ļ l			DERWENT;	
			IBM_TDB	

	202	(29/835).CCLS.	USPAT;	2004/05/01 16:05
-	203	(29/835).CCLS.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	•
			IBM_TDB	
	24	29/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and	USPAT;	2004/05/01 16:06
-	24	(temperature near20 compensation)	US-PGPUB;	
		(temperature nearzo compensation)	EPO; JPO;	
			DERWENT,	
			IBM_TDB	
	10	.156/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and	USPAT;	2004/05/01 16:19
= .	10	(temperature near20 compensation)	US-PGPUB;	
		(temperature neurzo componeduen)	EPO; JPO;	
			DERWENT,	
			IBM_TDB	,
	1	83/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and	USPAT;	2004/05/01 16:07
-] . ' [(temperature near20 compensation)	US-PGPUB;	
		(temperature nearzo componication)	EPO; JPO;	
	1	•	DERWENT;	
	1		IBM_TDB	
	393	(29/833).CCLS.	USPAT;	2004/05/01 18:17
_	393	(20/000).0000.	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
	1	156/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and	USPAT;	2004/05/02 10:17
ļ. -	1	(deformation near20 compensation)	US-PGPUB;	
		(deloffiation flear20 compensation)	EPO, JPO;	
			DERWENT;	
'		,	IBM_TDB	
	0	83/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and	USPAT;	2004/05/01 16:20
-	"	(deformation near20 compensation)	US-PGPUB;	
		(delotifiation fleatzo compensation)	EPO; JPO;	
			DERWENT;	
		·	IBM_TDB	
	1	29/\$.ccls. and (TAB or (tape and attach\$5 and bond\$4)) and	USPAT;	2004/05/01 16:20
-	1	(deformation near20 compensation)	US-PGPUB;	
		(delormation nearzo compensation)	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
	120	matsushita.asn. and (ACF)	USPAT;	2004/05/02 10:56
-	120	maisusina.asii. anu (AOI)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
1			IBM TDB	
	87	(83/75.5).CCLS.	USPAT;	2004/05/01 18:18
-	6/	(66/70.0).0020.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	65	(83/76.4).CCLS.	USPAT;	2004/05/01 18:20
1 -	05	(00/70.4).0000.	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	298	(83/364).CCLS.	USPAT;	2004/05/01 18:20
-	790	(00/004).0020.	US-PGPUB;	
		1	EPO; JPO;	
			DERWENT;	
1			IBM_TDB	
	0	118/\$.ccls. and (adhesive near3 dispens\$4) and (deformation	USPAT;	2004/05/02 10:45
-	1 0	near20 compensation)	US-PGPUB;	
1		Hearzo compensation)	EPO; JPO;	
				i contract of the contract of
			DERWENT;	l .

-	0	1 440/6		
	, 0	118/\$.ccls. and (adhesive near3 dispens\$4) and (size near20	USPAT;	2004/05/02 10:46
		comparation)	US-PGPUB;	
		•	EPO; JPO; DERWENT;	
			IBM_TDB	
_	1	118/\$.ccls. and (adhesive near3 dispens\$4) and (size near20	USPAT;	2004/05/02 10:45
	•	compensation)	US-PGPUB;	2004/03/02 10.45
		·	EPO; JPO;	
			DERWENT:	
			IBM_TDB	
-	0	118/\$.ccls. and (adhesive near3 dispens\$4) and (size near20	USPAT;	2004/05/02 11:47
		comparision)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	.		IBM_TDB	
-	9	fuji.asn. and (ACF)	USPAT;	2004/05/02 10:56
			US-PGPUB;	
.			EPO; JPO;	
	'		DERWENT;	
	ا م	full con and (anicotronic man) and and deviation	IBM_TDB	0004/05/00 11 55
-	3	fuji.asn. and (anisotropic near3 tape) and conductive	USPAT;	2004/05/02 11:22
		•	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM_TDB	
_	52	(700/303).CCLS.	USPAT;	2004/05/02 11:27
1	72	1. 1. 1. 2. 2. 2. 2. 2. 2. 2. 2. 2. 2. 2. 2. 2.	US-PGPUB;	200-1100/02 11.27
			EPO; JPO;	
			DERWENT;	
	j		IBM_TDB	
-	180	(700/302).CCLS.	USPAT;	2004/05/02 11:48
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	700/\$.ccls. and (adhesive near3 dispens\$4) and (size near20	USPAT;	2004/05/02 14:39
		comparision)	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	اه	702/\$.ccls. and (adhesive near3 dispens\$4) and (size near20	IBM_TDB USPAT;	2004/05/02 14:40
	0	comparision)	US-PGPUB;	2004/03/02 14.40
		on panelon,	EPO; JPO;	
			DERWENT;	
'		·	IBM_TDB	
-	0	700/\$.ccls. and (anisotropical near3 tape)	USPAT;	2004/05/02 11:48
		. , , ,	US-PGPUB;	_
			EPO; JPO;	
			DERWENT;	,
			IBM_TDB	
-	97	(702/97).CCLS.	USPAT;	2004/05/02 11:58
			US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
	327	(702/158).CCLS.	IBM_TDB	2004/05/02 40:40
=	321	(1021130).CCE3.	USPAT; US-PGPUB;	2004/05/02 12:18
		·	EPO; JPO;	
		İ	DERWENT;	
			IBM_TDB	
- 1	102	(702/101) CCLS.	USPAT;	2004/05/02 12:18
		` '	US-PGPUB;	
			EPO; JPO;	
		, and the second	DERWENT;	
1			DC:\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	

				2004/05/00 44 00
-	18 0	118/\$.ccls. and ciardella 700/\$.ccls. and (adhesive near3 dispens\$4) and (size near20 comparison)	USPAT USPAT; US-PGPUB;	2004/05/02 14:26 2004/05/02 14:40
			EPO; JPO; DERWENT; IBM_TDB	
-	0	702/\$.ccls. and (adhesive near3 dispens\$4) and (size near20 comparison)	USPAT; US-PGPUB;	2004/05/02 14:40
			EPO; JPO; DERWENT; IBM_TDB	
-	6	700/\$.ccls. and (adhesive near3 dispens\$4) and (size near20 control)	USPAT; US-PGPUB;	2004/05/02 14:41
			EPO; JPO; DERWENT; IBM_TDB	
-	3	702/\$.ccls. and (adhesive near3 dispens\$4) and (size near20 control)	USPAT; US-PGPUB; EPO; JPO;	2004/05/02 14:42
			DERWENT; IBM_TDB	
-	4	702/\$.ccls. and (adhesive near3 dispens\$4) and (location near20 control)	USPAT; US-PGPUB; EPO; JPO;	2004/05/02 14:42
			DERWENT; IBM_TDB	2004/05/02 14:43
-	9	700/\$.ccls. and (adhesive near3 dispens\$4) and (location near20 control)	USPAT; US-PGPUB; EPO; JPO;	2004/03/02 14.43
	28	118/\$.ccls. and (adhesive near3 dispens\$4) and (location	DERWENT; IBM_TDB USPAT;	2004/05/02 18:43
	20	near20 control)	US-PGPUB; EPO; JPO;	
_	40	156/\$.ccls. and (adhesive near3 dispens\$4) and (location	DERWENT; IBM_TDB USPAT;	2004/05/02 14:45
		near20 control)	US-PGPUB; EPO; JPO; DERWENT;	
-	0	118/\$.ccls. and (resin near3 dispens\$4) and (location near20	IBM_TDB USPAT;	2004/05/02 18:43
		weight)	US-PGPUB; EPO; JPO; DERWENT;	
_	0	118/\$.ccls. and (ACF near3 dispens\$4) and (location_near20_weight)	IBM_TDB USPAT; US-PGPUB;	2004/05/02 18:43
		weight)	EPO; JPO; DERWENT;	
-	6	118/\$.ccls. and (adhesive near3 dispens\$4) and (location near20 weight)	IBM_TDB USPAT; US-PGPUB;	2004/05/02 18:45
			EPO; JPO; DERWENT; IBM_TDB	
-	0	118/\$.ccls. and (adhesive near3 dispens\$4) and (location near20 mass)	USPAT; US-PGPUB;	2004/05/02 19:33
			EPO; JPO; DERWENT; IBM_TDB	

<u>-</u>	0	118/\$.ccls. and (adhesive near3 dispens\$4) and (leadframe)	USPAT;	2004/05/02 19:33
		·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18	118/\$.ccls. and (leadframe)	USPAT;	2004/05/02 19:36
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
ļ	i i		IBM_TDB	
-	79	156/\$.ccls. and (leadframe)	USPAT;	2004/05/02 19:36
			US-PGPUB;	
			EPO; JPO;	
1			DERWENT;	
			IBM_TDB	

L Number	Hits	Search Text	DB	Time stamp
15	1177	(156/64).CCLS.	USPAT;	2004/05/03 11:49
		·	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
İ	-	• •	IBM_TDB	
16	354	(156/358).CCLS.	USPAT;	2004/05/03 11:49
.			US-PGPUB;	
ļ			EPO; JPO;	
i			DERWENT;	
			IBM_TDB	
17	183	(156/367).CCLS.	USPAT;	2004/05/03 11:49
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
18	95	(156/368).CCLS.	USPAT;	2004/05/03 11:49
			US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
		•	IBM_TDB	0004/05/00 44 50
30	807	(156/361).CCLS.	USPAT;	2004/05/03 11:50
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/00 44 50
32	617	(156/378) CCLS.	USPAT;	2004/05/03 11:50
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/02 44:50
39	1	("5564183").PN.	USPAT	2004/05/03 11:50
19	169	(156/379).CCLS.	USPAT;	2004/05/03 11:50
1			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/05/02 11:50
20	8	(((156/64).CCLS.) ((156/353).CCLS.) ((156/358).CCLS.)	USPAT	2004/05/03 11:50
!		((156/359).CCLS.) ((156/360).CCLS.) ((156/361).CCLS.)		
		((156/367).CCLS.) ((156/368).CCLS.) ((156/378).CCLS.)		
		((156/379).CCLS.)) and ((circuit or chip or semicondutor or		
		die or electrode) same (bond or weld or attach or		
1		attachment)) and ((temperature or heat or thermal) same		
	ļ	(correlation or correction or calibration))	LIC DODLID:	2004/05/03 11:50
21	4	(((156/64).CCLS.) ((156/353).CCLS.) ((156/358).CCLS.)	US-PGPUB; EPO; JPO;	2004/03/03 11.00
		((156/359).CCLS.) ((156/360).CCLS.) ((156/361).CCLS.)	DERWENT;	
		((156/367).CCLS.) ((156/368).CCLS.) ((156/378).CCLS.)	IBM TDB	
		((156/379).CCLS.)) and ((circuit or chip or semicondutor or	I IDIVI_I DD	
		die or electrode) same (bond or weld or attach or		
		attachment)) and ((temperature or heat or thermal) same		
		(correlation or correction or calibration))	USPAT;	2004/05/03 11:50
22	59	(29/\$.ccls.) and ((circuit or chip or semicondutor or die or	US-PGPUB;	2004/00/00 11:00
		electrode) same (bond or weld or attach or attachment)) and	EPO; JPO;	
		((temperature or heat or thermal) same (correlation or	DERWENT;	
1 .		correction or calibration))	IBM_TDB	
		(450/6 1) and (/ simple property of the prope	USPAT;	2004/05/03 11:50
23	41	(156/\$.ccls.) and ((circuit or chip or semicondutor or die or	US-PGPUB;	2004,00/03 11.00
		electrode) same (bond or weld or attach or attachment)) and	EPO; JPO;	
		((temperature or heat or thermal) same (correlation or	DERWENT;	
		correction or calibration))	IBM TDB	
1	1		I DIM I DB	<u> </u>

			11004=	0004/05/50 11.55
24	72	(438/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 11:50
25	30	(700/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 11:50
26	58	(702/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 11:50
27	375	(156/353).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
28	418	(156/359).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 11:51
29	210	(156/360).CCLS.	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 11:51
31	5	(((156/361) CCLS.)) and ((circuit or chip or semicondutor or die or electrode)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
33	9	(((156/378) CCLS.)) and ((circuit or chip or semicondutor or die or electrode)) and ((temperature or heat or thermal) same (correlation or correction or calibration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
34	66	(29/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
35	18	(156/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
36	118	(438/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51
37	11	(700/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/05/03 11:51
38	21	(702/\$.ccls.) and ((circuit or chip or semicondutor or die or electrode) same (bond or weld or attach or attachment)) and ((temperature or heat or thermal) same (compensation))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/03 11:51

40 11 "5564183" USPAT 2004/05/03 11:51